

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7,121,926 B2
APPLICATION NO. : 10/028616
DATED : October 17, 2006
INVENTOR(S) : Gundu M. Sabde

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page item (56), Page 2, under Foreign Patent Documents, delete "WO 99/553532" and insert --WO 99/53532--.

Column 6, line 11, insert the following paragraph -- It is to be understood that a planarization composition suitable for use in the methods of the present invention is preferably essentially free of abrasive particles when supplied to the interface of the fixed abrasive article and the workpiece surface. However, it is contemplated that planarization is accomplished by one or both of the fixed abrasive article and/or abrasive particles that may be removed from the fixed abrasive article at the fixed abrasive/surface interface in combination with the planarization composition. In any event, abrasive particles are typically not present in the composition as initially applied, i.e., they are not supplied from a source external to the polishing interface-- .

Column 9, line 29, Claim 10, delete "plan".

Signed and Sealed this

Ninth Day of January, 2007

A handwritten signature in black ink, appearing to read "Jon W. Dudas", is written over a faint, larger signature that appears to read "Jon W. Dudas".

JON W. DUDAS
Director of the United States Patent and Trademark Office